

SWITCH PIN

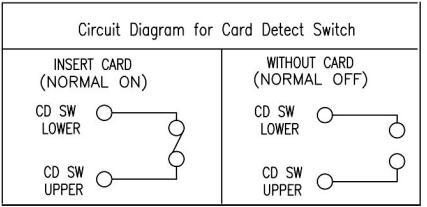
Sim Card  
SIM Card Center

Before Working

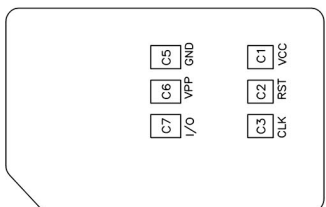
After Working

RECOMMENDED PCB LAYOUT(TOP VIEW)  
GENERAL TOLERANCES:±0.05

- SOLDER AREA
- NONE CIRCUIT DIAGRAM AREA



NOTES:  
1)MATERIAL:  
HOUSING: LCP UL 94V-0  
CONTACT: C5210R-H,T=0.15  
SHELL: SUS304,T=0.20  
MYLAR: POLYESTER  
2)FINISH:  
CONTACT:GOLD FLASH PLATED ON CONTACT AREA;  
GOLD FLASH PLATING ON SOLDER TAILS, WITH  
ENTIRE CONTACT UNDERPLATED 50u\*Min. NICKEL  
SHELL: 30u\*Min. NICKEL UNDERPLATED OVERALL ,  
GOLD FLASH PLATED ON SOLDER TAILS  
3.INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10



| PIN NO. | DESCRIPTION |
|---------|-------------|
| P1#     | C1:VCC      |
| P2#     | C5:GND      |
| P3#     | C2:RST      |
| P4#     | C6:VPP      |
| P5#     | C3:CLK      |
| P6#     | C7:I/O      |
| P7#     | POL         |
| P8#     | DET         |

RoHS  
Compliant

**HSM** 玄茂科技股份有限公司  
**HSUAN MAO TECHNOLOGY CO., LTD.**

APPD.  
核准  
Betty  
DATE 制表日  
2019/05/17

SCALE  
比例 参考  
UNIT  
單位 M M  
PAGE  
張數 1 OF 1

TOLERANCE:  
X.X ±0.30  
X.XX ±0.25  
X.XXX ±0.15  
X: ±2 X.X: ±0.5  
SIZE:  
紙張尺寸 A 4  
REV.  
版次 A  
PART NAME 品名  
SIM CARD CONNECTOR PUSH-PUSH TYPE  
SMT TYPE H=1.85mm 6+2P(WITH SWITCH)  
GOLD FLASH PLATING WITH POST  
BLACK COLOR REEL PACKING ROHS  
PART NO.  
料號 C0662-06YGBR00R